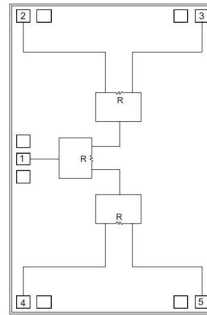


Performance

- Frequency: 12~18GHz
- Insertion loss: 0.8dB
- Chip size: 2.60*1.50*0.1mm

Function Diagram

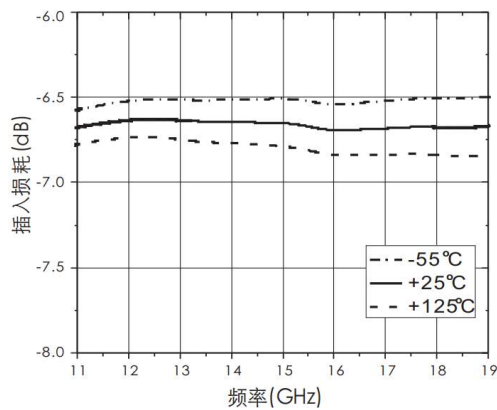


Electrical Specifications (Ta=+25°C, 50Ω system)

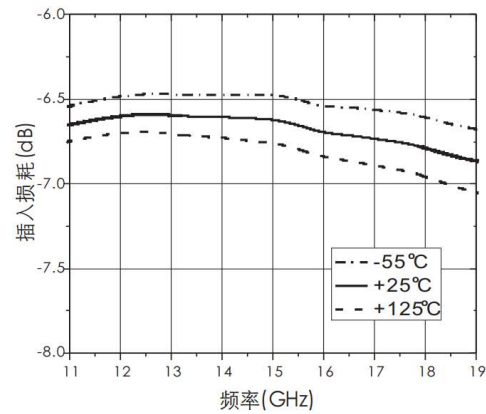
Parameter	Min	Typical	Max	Unit
Frequency Range		12~18		GHz
Insertion Loss	-	0.7	0.9	dB
Insertion Loss Ripple	-	±1	-	dB
Isolation	18	20	-	dB
Input Return Loss	15	20	-	dB
Output Return Loss	15	20	-	dB

Test Curves

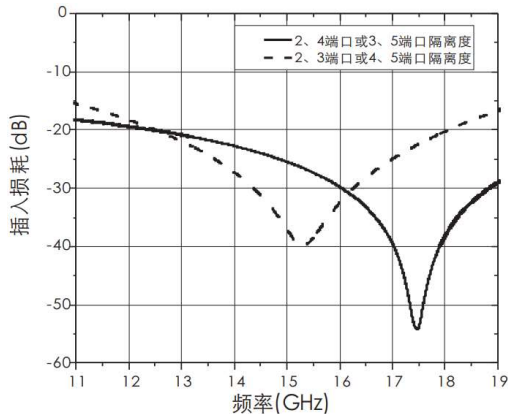
2/4 Port Insertion loss vs. Freq



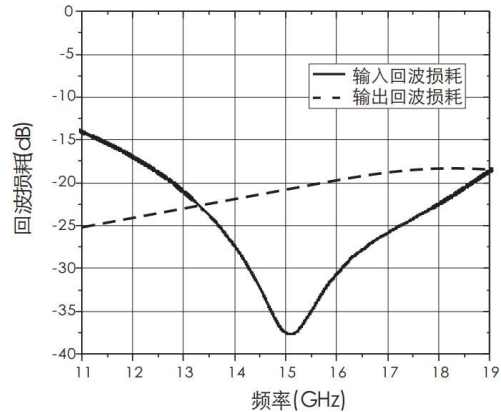
3/5 Port Insertion loss vs. Freq



Isolation vs. Freq



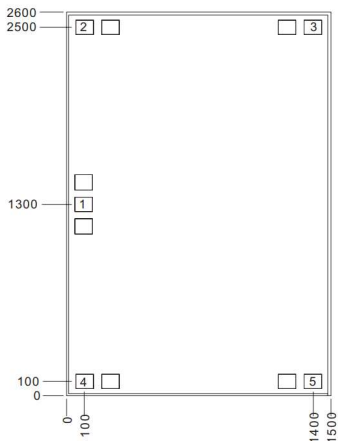
Input/Output Return Loss vs. Freq



Absolute Max Ratings

Parameter	Value
Input Signal Power	+33dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C
Static protection Grade (HBM)	Class 1A

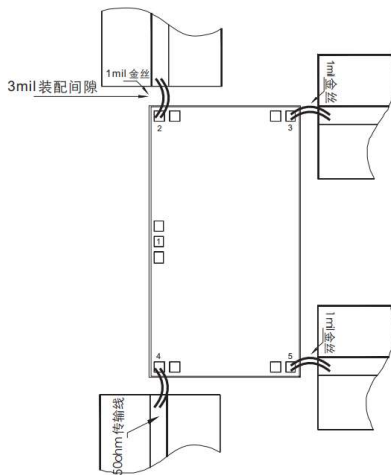
Outline Size



Note:

1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated
Pads size: 100*100 um
5. Don't bonding on thru holds
6. Tolerance: ±50um

Assembly Diagram



Bonding Definition

No.	Number	Description
1	IN	RF input, 50ohm
2,3,4,5	Out1,Out2 Out3,Out4	RF output, 50ohm
	GND	Bottom must be grounded